

# EDFAS FA Workshop

Venue: National University of Singapore, Block E7, #03-08/09, Seminar Room 3/4,  
15 Kent Ridge Crescent Singapore 119276

**Friday, 17 July 2026**

National University of Singapore (NUS) SHINE and EDFAS have jointly organized the inaugural ASEAN Failure Analysis workshop in Singapore with industry collaboration and sponsorship from SEMICAPS. The workshop will bring together leading industry partners, vendors, and academia for a day of activities that introduce, discuss, and share the most cutting-edge advancements in the industry. Following the workshop, there will be a panel discussion with experts, followed by a networking session for engineers, students, and experts.

\*\*Seating is limited, and registration is required for entry. Unfortunately, walk-ins will not be accepted.

\*\*Please RSVP to [rsvp@semicaps.com](mailto:rsvp@semicaps.com) by 8 July 2026. You will receive an email confirmation for registration.

## INTRODUCTION

08:45am	09:15hrs	<b>REGISTRATION</b>		
09:15am	09:30hrs	<b>OPENING</b>	Prof. Lim Yeow Kheng	Introduction: NUS-Shine
			Ms. Rose M. Ring	EDFAS and Workshop Agenda

## TECHNICAL PRESENTATIONS

**Time Start**      **Time End**

09:30hrs      10:05hrs  
**Speaker**      Dr. Wen-Hsien Chuang, Technical Director of New Technology Product Infrastructure Division, TSMC  
**Topic**      The Future of Failure Analysis: Gaps and Strategies for Emerging Semiconductor Innovations

10:05hrs      10:40hrs  
**Speaker**      Ms. Susan Li, Technical Director, Marvell Technology  
**Topic**      Advanced Packaging Overview and Failure Analysis Challenges

10:40hrs      10:55hrs      **BREAK**

10:55hrs      11:30hrs  
**Speaker**      Ms. Grace Tan, Director of Engineering/Failure Analysis, Qualcomm/Singapore  
**Topic**      FA on the Automotive Edge

11:30hrs      12:05hrs  
**Speaker**      Dr. Mike Bruce, VP of Applications and Engineering, SEMICAPS  
**Topic**      EFA Basics, Challenges, Innovations, and Roadmap

12:05hrs      12:45hrs      **LUNCH**



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## TECHNICAL PRESENTATIONS

Time Start	Time End	
12:45hrs	13:20hrs	
<b>Speaker</b>	Mr. Benny Hsu, Senior Device Analysis Engineer, AMD/USA	
<b>Topic</b>	From Monolithic to Chiplet to Module: The New Frontier of Fault Isolation	
13:20hrs	13:55hrs	
<b>Speaker</b>	Professor Jeroen Anton Van Kan, Founder of Anoton Technology, National University of Singapore	
<b>Topic</b>	Proton Microscopy for Advanced Semiconductor Failure Analysis and Subsurface Characterization	
13:55hrs	14:25hrs	
<b>Speaker</b>	Dr. Joseph Liao, Founder and Chief Technology Officer, EnliTech	
<b>Topic</b>	Spectral Imaging–Based Optical Loss Mapping for Efficient Failure Analysis and Wafer-Level Screening of Silicon Photonic Integrated	
14:25hrs	14:55hrs	
<b>Speaker</b>	Dr. Marc Heinemann, Team Leader/Failure Analysis, SmarAct Metrology	
<b>Topic</b>	Nanoprobing for Defect Localization	
14:55hrs	15:25hrs	
<b>Speaker</b>	Mr. Greg Johnson, Senior Applications Development Engineer, Zeiss	
<b>Topic</b>	SEM Passive Voltage Contrast	
15:25hrs	15:40hrs	<b>BREAK</b>

15:40hrs 16:40hrs

## PANEL DISCUSSION

**Moderator:** Prof. Lim Yeow Kheng

### Panelists

Dr. Wen-Hsien Chuang, TSMC

Ms. Grace Tan, Qualcomm

Dr. Mike Bruce, SEMICAPS

Prof. Jeroen Anton Van Kan, NUS

**Panel Title:** Closing the Failure Analysis Gap for the AI-Era Semiconductor Industry

### Perspectives

Foundry perspective on advanced semiconductor technology trends and emerging failure analysis gaps

Automotive and application-driven reliability, with a focus on failure analysis challenges

Electrical failure analysis and FA tool development roadmap

Advanced characterization techniques and academic research capabilities

16:40hrs 17:00hrs **FINALE**

17:00hrs 18:00hrs **NETWORKING**



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